



Statement of Materials, Construction

LEAD-FREE -- 26L-DFN -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	29.12280	Cu	7440-50-8	28.39473	37.91576	97.50
				Fe	7439-89-6	0.67565	0.90220	2.32
				Zn	7440-66-6	0.03495	0.04667	0.12
				P	7723-14-0	0.00874	0.01167	0.03
				Ag	7440-22-4	0.00874	0.01167	0.03
2	Die	Silicon Chip	0.28130	Si	7440-21-3	0.27989	0.37374	99.50
3	Die Attach Material	Conductive Epoxy	0.17040	Epoxy Resin	9003-36-5	0.01602	0.02139	9.40
				Silver	7440-22-4	0.12269	0.16383	72.00
				Epoxy	Proprietary	0.02556	0.03413	15.00
				Amine	Proprietary	0.00204	0.00273	1.20
				Gamma Butyrolactone	112-07-2	0.00204	0.00273	1.20
				Metal Oxide	Proprietary	0.00204	0.00273	1.20
4	Wire	Gold	0.21800	Au	7440-57-5	0.21798	0.29107	99.99
5	Lead Finish	Tin	0.86620	Sn	7440-31-5	0.86620	1.15665	100
6	Encapsulation	Epoxy Resin	44.23030	Fused Silica	7631-86-9	41.44379	55.34029	93.70
				Epoxy Resin	Proprietary	1.32691	1.77183	3.00
				Phenol Resin	Proprietary	1.32691	1.77183	3.00
				Carbon Black	1333-86-4	0.13269	0.17718	0.30
Total Package Weight			74.88900					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%